SPECIFICATION

COMMERCIALLY AVAILABLE

ITEM: CERAMIC DUPLEXER
PART NUMBER: CFDM-1880196010A

RoHS

For SMA see FNP-1215

ISSUED	CHECKED	CHECKED	CHECKED	APPROVED
10/15/2019(ASM)				

***FILTRO**NETICS Inc*

1. APPLICATION

THIS SPECIFICATION APPLIES TO A BAND PASS DUPLEX FILTER, USING DIELECTRIC RESONATORS.

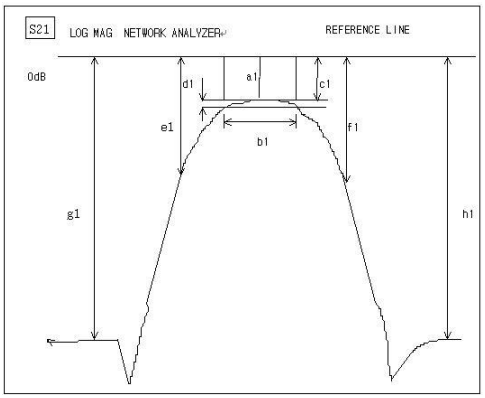
2. PART NUMBER

PART NO	CFDM-1880196010A
PACKAGING	PLASTIC TRAY

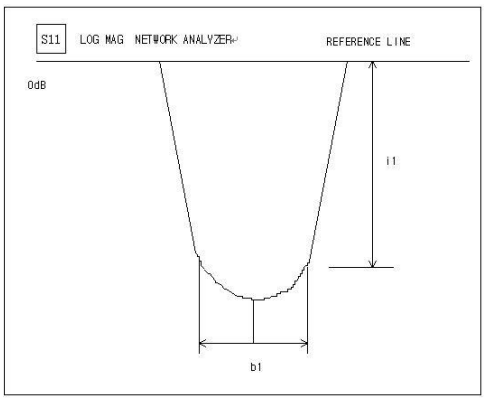
3. SPECIFICATIONS

Parameter	Unit	Specification	
		Low Path	High Path
Center Frequency	MHz	1880	1960
Bandwidth	MHz	Fo ± 30 (1850 ~ 1910MHz)	Fo ± 30 (1930 ~ 1990MHz)
Insertion Loss in BW	dB	3.0 Max.	
Ripple in BW	dB	2.3 Max.	
Return Loss in BW	dB	12 Min.	
Attenuation	dB	50 Min. @ 1930 ~ 1990MHz	50 Min. @ 1850 ~ 1910MHz
Input Power	Watt	3.0 Max.	
IN/OUT Impedance	Ω	50	
Operating Temp. Range	˚C	-40 ~ +85	

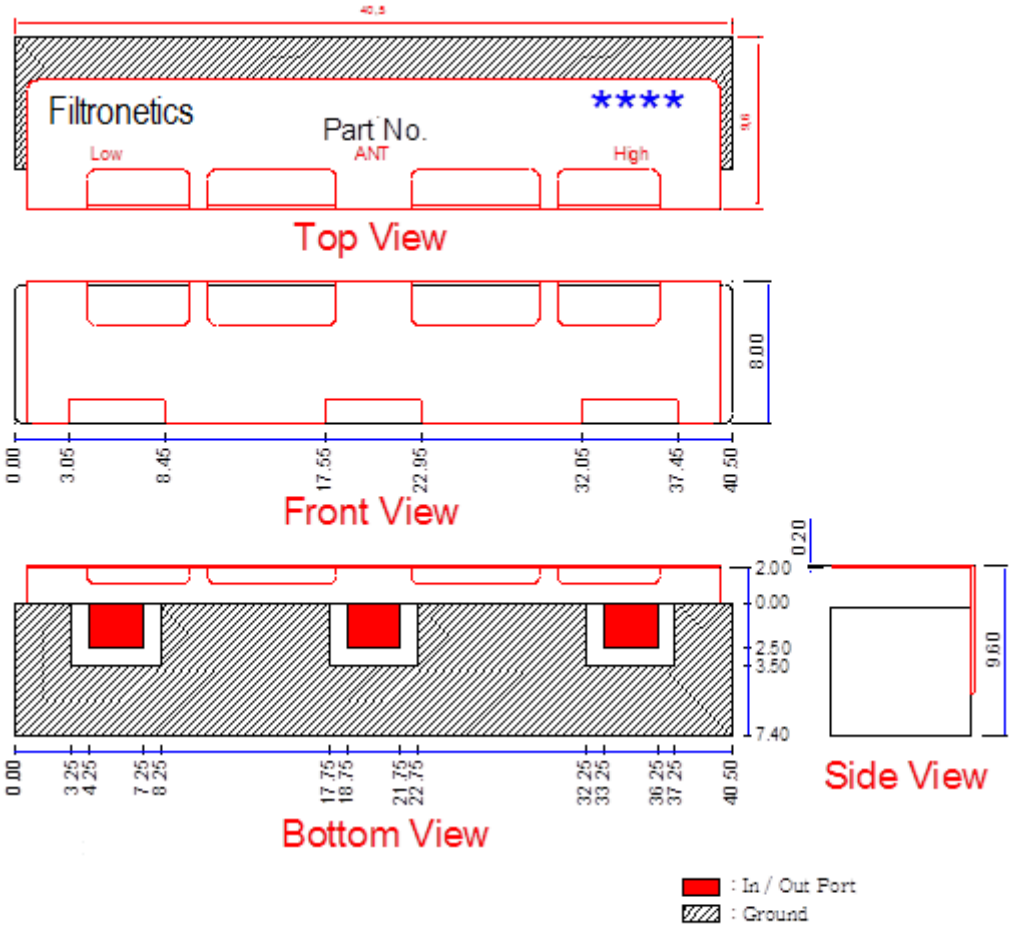
S21 LOG MAG NETWORK ANALYZER



S11 LOG MAG NETWORK ANALYZER



4. DIMENSIONS:



MATERIAL SPECIFICATION

2. METAL CASE
   1) MATERIAL: Sn
3. RESONATOR
   1) COATING MATERIAL: Ag
4. ROHS Compliant

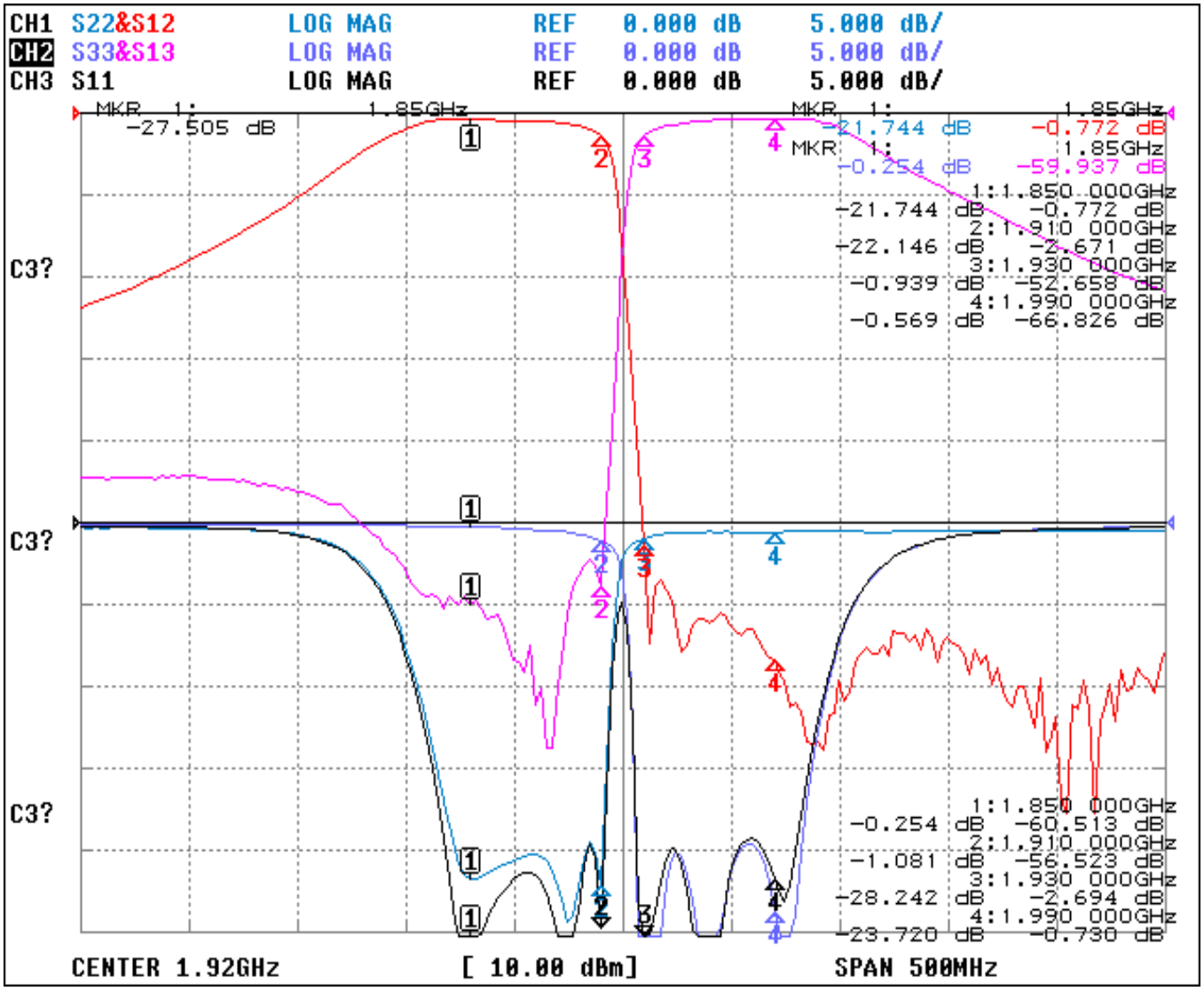
MARKING (Laser)
CFDM-1880196010A
Filtronetics
Date Code (YYWW)

UNIT: MM
TOLERANCE: +/-0.3MM

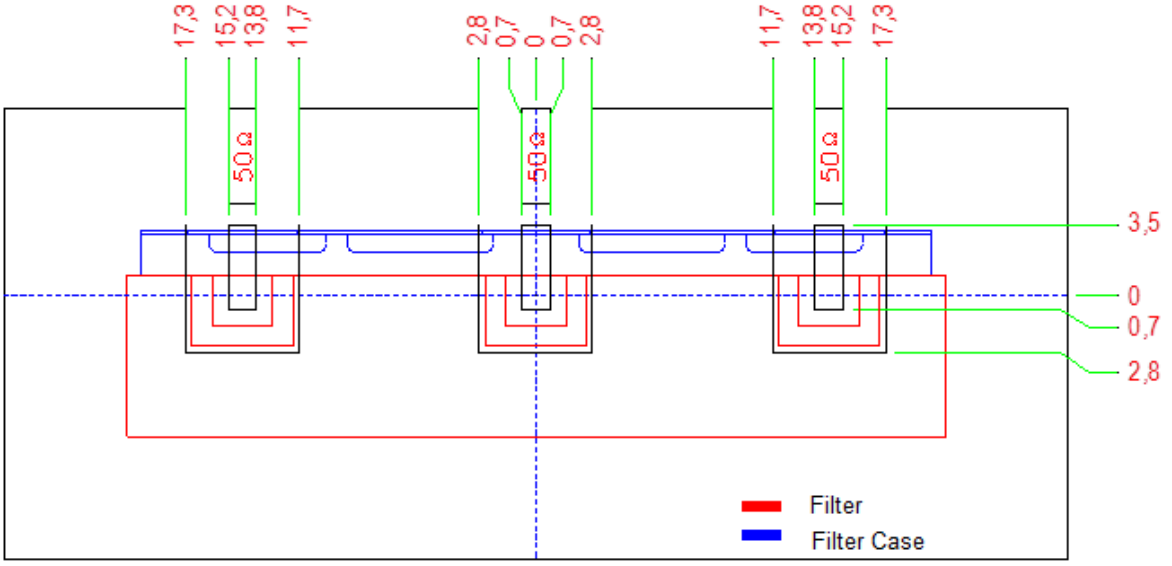
- CAUTIONS:

1. Max reflow temperature 230°C for 10 sec.
2. If boards are cleaned after installation units must be completely dried.
3. When handling products, be careful not to damage the outer-electrode.
4. When handling products be careful not to touch the outer-electrode with bare hands or solder-ability is reduced.
5. Do not apply excessive pressure or shock to product in handling or in transportation or damage to the ceramic filters may result.

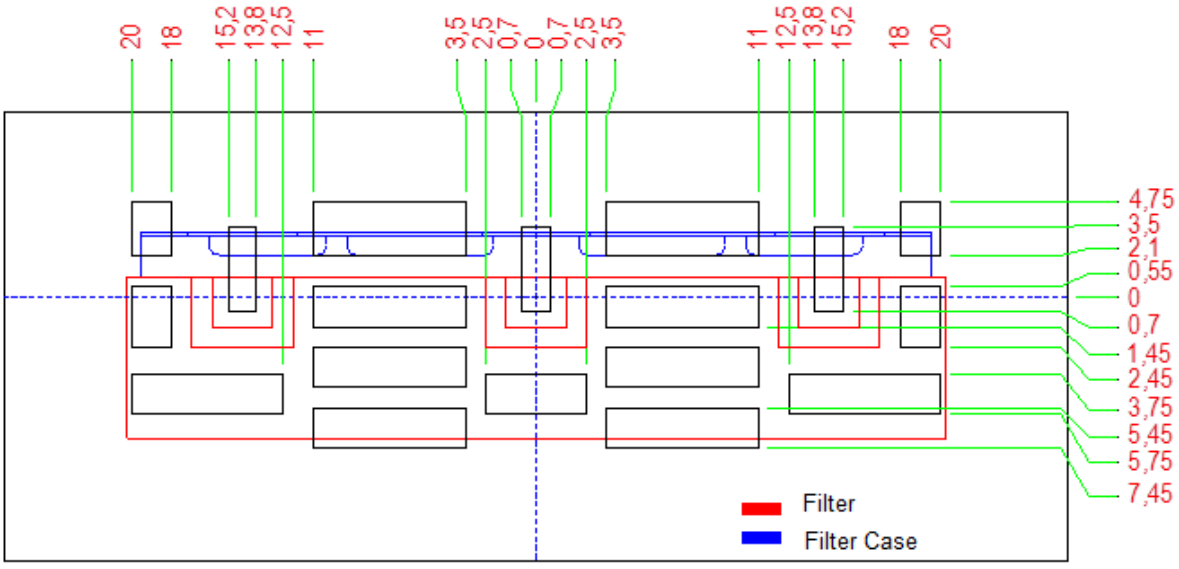
5. PERFORMANCE GRAPHS:



LAND PATTERN



Recommended land pattern



Recommended resist pattern

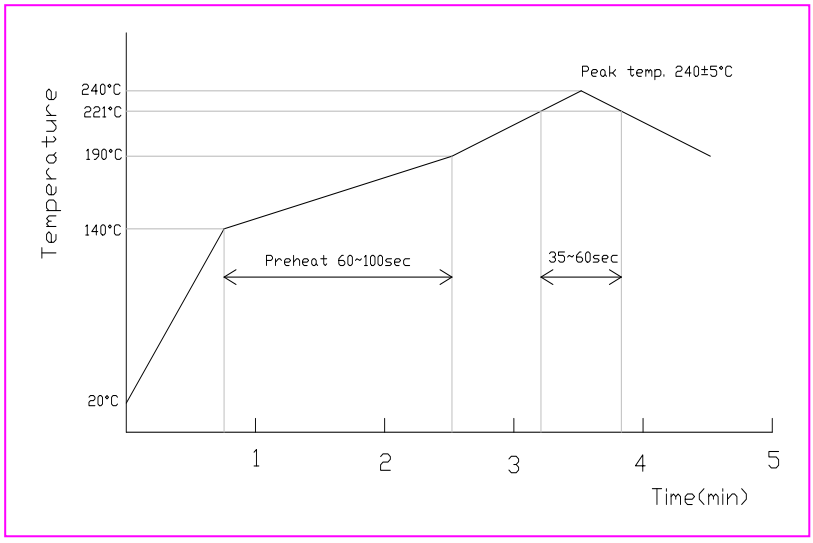
6. DEFINITIONS:

TERMS	DESCRIPTION	SPECIFICATION
Center Frequency	The midpoint of through band pass filter pass band, normally expressed as the arithmetic mean of the -3db point. Also called fo.	3. SPECIFICATION
Pass Band Width	The width of the pass band of a filter referenced to the minimum insertion loss point in the pass band. The pass band of a filter is stated as -1.0dB bandwidth.	
Insertion Loss	The loss of the filter, in db, measured at center frequency relative to a through line (0 dB).	
Attenuation	Reduction of RF power through a filter measured in dB, at desired band and referenced to 0 dB. (Filter to be removed from circuit)	
Pass Band Ripple	Variations in loss in the pass band of the filter, superimposed upon the fundamental shape of the pass band.	
V.S.W.R in Pass Band	The ratio of the maximum value of a standing wave to its minimum value, related to the return loss in pass band.	

7. RELIABILITY TEST AND CONDITIONS:

ITEM	TEST CONDITIONS	REQUIREMENTS
Resistance to solder heat	Preheat temperature : 120 to 150°C Preheat time: 1 to 1.5 min Solder temperature: 260 +/- 10°C Dipping time: 10 +/- 0.5 sec	No damage such as cracks should be caused in chip element.
Solderability	Preheat temperature: 120 to 150°C Preheat time: 1 to 1.5 min Solder temperature: 235 +/- 5°C Dipping time: 5 +/- 1 sec	More than 80% of the terminal electrode shall be covered with new solder
Heat resistance (High-temperature Load)	Temperature: 85 +/- 2°C Applied voltage: Rated voltage Applied current: Rated current Recovery: 1 to 2hrs of recovery under the standard condition after the removal from test chamber.	No mechanical damage. After test, the device shall satisfy the specification in section 3.
Thermal shock (Temperature cycle)	Conditions for 1 cycle Step 1: + 85°C 15 min Step 2 : - 30°C 15 min Number of cycle: 10	No mechanical damage. After test, the device shall satisfy the specification in section 3.
Humidity Resistance	Temperature: 40 +/- 2°C Humidity: 90 to 95% RH Duration: 96 +/- 5 hrs Recovery: 1 to 2hrs of recovery under the standard condition after the removal from test chamber.	No mechanical damage. After test, the device shall satisfy the specification in section 3.
Vibration	Frequency: 10 ~ 50 Hz Amplitude: 1.52 ㎜ (0.060 inches) Direction: X, Y and Z Time: each 30 min for all directions	No mechanical damage. After test, the device shall satisfy the specification in section 3.

8. REFLOW SOLDERING STANDARD CONDITIONS



- Measuring point of temperature in-out terminals of the device.
- Reflow Soldering
- Both convection and infrared rays
- Hot air
- Solder Cream: Sn96.5/Ag3.5